## MSKSEMI















**ESD** 

TVS

TSS

MOV

**GDT** 

**PLED** 

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SLP2510P8

#### **Features**

- 60Watts peak pulse power (tp = 8/20µs)
- Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance (Cj=0.2pF typ. I/O to I/O)
- IEC 61000-4-2 ±20kV contact ±25kV air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4A (8/20μs)

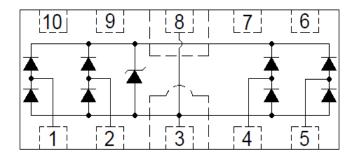
#### **Mechanical Data**

- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

## **Applications**

- USB3.0, USB2.0, Ethernet
- HDMI 2.0, Displayport 1.3,eSATA
- Unified Display interface
- Digital Visual Interface
- High speed serial interface

## Schematic & PIN Configuration

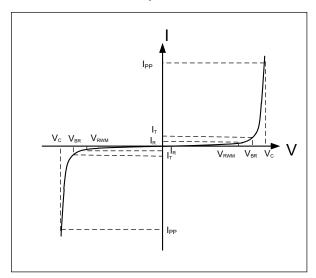


### **Electrical Characteristics**

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{RWM}$				5.0	V
Reverse Breakdown Voltage	$V_{BR}$	I <sub>T</sub> =1mA	6.0			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =5V,T=25℃			1	μΑ
Peak Pulse Current	I <sub>PP</sub>	tp =8/20μs			4	Α
Clamping Voltage	V <sub>C</sub>	I <sub>PP</sub> =4A,t <sub>p</sub> =8/20μs			15	V
Junation Canacitanas	C <sub>j</sub>	V <sub>R</sub> = 0V, f = 1MHz I/O to I/O		0.2	0.3	nE
Junction Capacitance		V <sub>R</sub> = 0V, f = 1MHz I/O to GND		0.4	0.55	pF

## **Electrical Parameters (TA = 25°C unless otherwise noted)**

	Parameter		
<b>I</b> PP	MaximumReversePeak Pulse Current		
Vc	Clamping Voltage @ IPP		
VRWM	WorkingPeak Reverse Voltage		
lr	Maximum Reverse Leakage Current @ VRWM		
V <sub>BR</sub>	Breakdown Voltage @ I⊤		
lτ	Test Current		



Note:.8/20  $\mu s$  pulse waveform.



## **Typical Characteristic Curves**

Fig.1 Peak Pulse Power Rating Curve

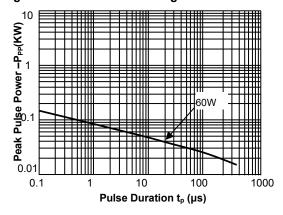


Fig.2 Pulse Derating Curve

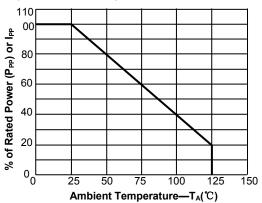


Fig.3 Pulse Waveform-8/20µs

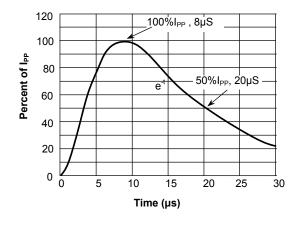
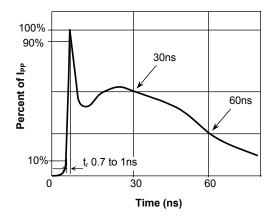


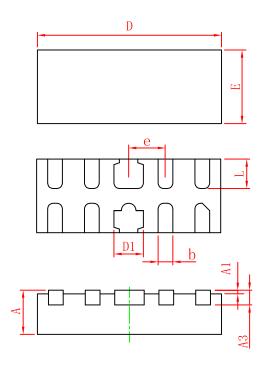
Fig.4 Pulse Waveform-ESD(IEC61000-4-2)



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#### **PACKAGE MECHANICAL DATA**



Symbol	Dimensions in millimeters					
Symbol	Min	Nom	Max			
Α	0.45	0.50	0.55			
A1	-	0.02	0.05			
A3	0.10	0.15	0.20			
D	2.45	2.50	2.55			
E	0.95	1.00	1.05			
D1	0.35	0.40	0.45			
b	0.15	0.20	0.25			
е	0.50BSC					
L	0.35	0.40	0.45			

#### **REEL SPECIFICATION**

P/N	PKG	QTY
RClamp0524P.TCT-MS	SLP2510P8	3000



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